

IRFR310B / IRFU310B

400V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

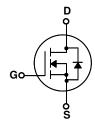
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies and electronic lamp ballasts based on half bridge.

Features

- 1.7A, 400V, $R_{DS(on)}=3.4\Omega$ @V_{GS} = 10 V Low gate charge (typical 7.7 nC)
- Low Crss (typical 6.0 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability







Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		IRFR310B / IRFU310B	Units
V _{DSS}	Drain-Source Voltage		400	V
I _D	Drain Current - Continuous (T _C = 25°	°C)	1.7	Α
	- Continuous (T _C = 100	O°C)	1.1	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	6.0	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	100	mJ
I _{AR}	Avalanche Current	(Note 1)	1.7	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	2.6	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		2.5	W
	Power Dissipation (T _C = 25°C)		26	W
	- Derate above 25°C	•	0.21	W/°C
T _J , T _{stg}	Operating and Storage Temperature Ra	nge	-55 to +150	°C
TL	Maximum lead temperature for soldering 1/8" from case for 5 seconds	purposes,	300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		4.76	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	\$	Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced	l to 25°C		0.4		V/°C
I _{DSS}	7 0	V _{DS} = 400 V, V _{GS} = 0 V				10	μΑ
Zero Gate Voltage Drain Current		V _{DS} = 320 V, T _C = 125°C)			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 0.85 \text{ A}$			2.7	3.4	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 0.85 \text{ A}$	(Note 4)		2.05		S
	ic Characteristics	,		1		1	1
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			250	330	pF
C _{oss}	Output Capacitance				30	40	pF
C _{rss}	Reverse Transfer Capacitance				6.0	8.0	pF
Switchi	ing Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 200 V, I _D = 2.0 A,			6.0	20	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$			25	60	ns
t _{d(off)}	Turn-Off Delay Time	- 1.G - 20 22			20	50	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		25	60	ns
Qg	Total Gate Charge	V _{DS} = 320 V, I _D = 2.0 A,			7.7	10	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V			1.5		nC
Q _{gd}	Gate-Drain Charge		(Note 4, 5)		3.2		nC
Drain-S	Source Diode Characteristics a	nd Maximum Rating	s				
I _S	Maximum Continuous Drain-Source Did	<u> </u>				1.7	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current				6.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.7 \text{ A}$				1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 2.0 \text{ A},$			210		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	(Note 4)		0.9		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 61 mH, I_{AS} = 1.7A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq 2.0A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

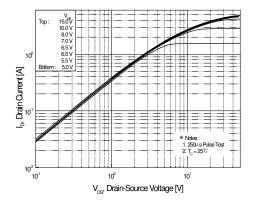


Figure 1. On-Region Characteristics

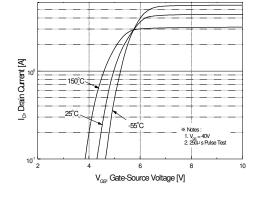


Figure 2. Transfer Characteristics

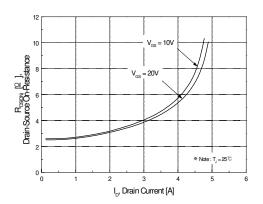


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

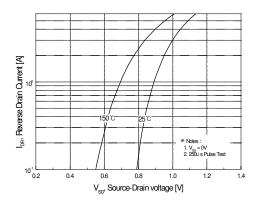


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

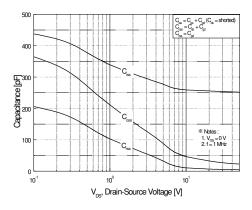


Figure 5. Capacitance Characteristics

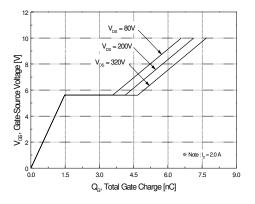


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

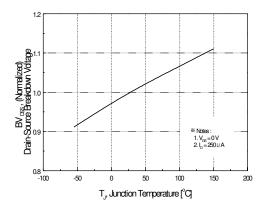


Figure 7. Breakdown Voltage Variation vs Temperature

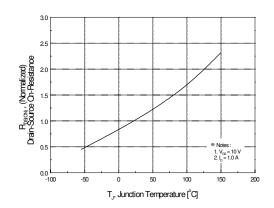


Figure 8. On-Resistance Variation vs Temperature

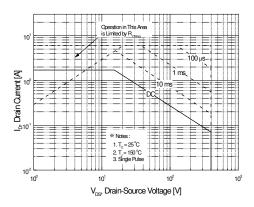


Figure 9. Maximum Safe Operating Area

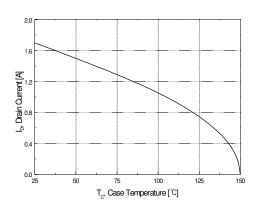


Figure 10. Maximum Drain Current vs Case Temperature

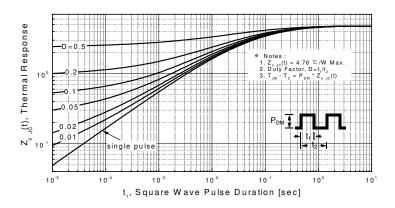
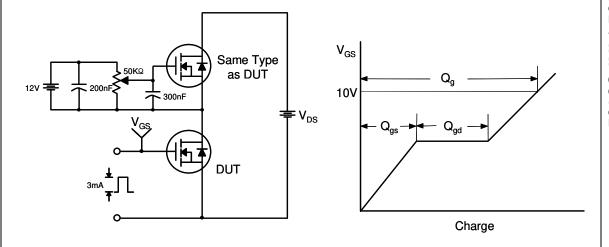


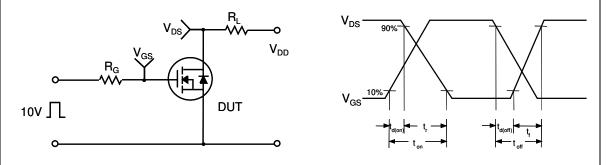
Figure 11. Transient Thermal Response Curve

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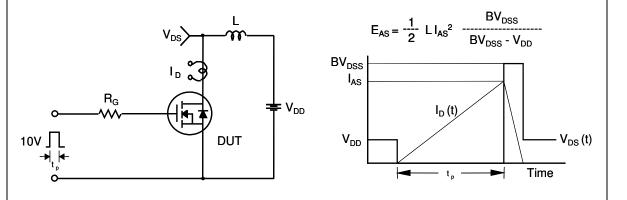
Gate Charge Test Circuit & Waveform



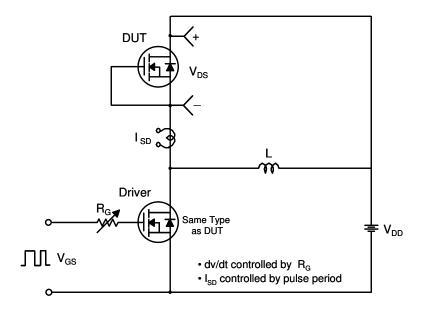
Resistive Switching Test Circuit & Waveforms

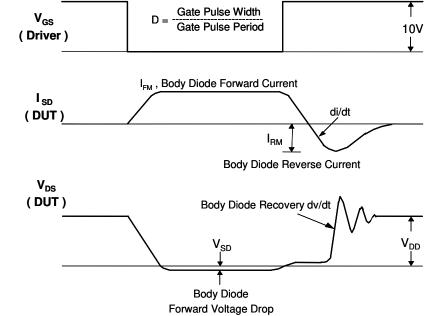


Unclamped Inductive Switching Test Circuit & Waveforms

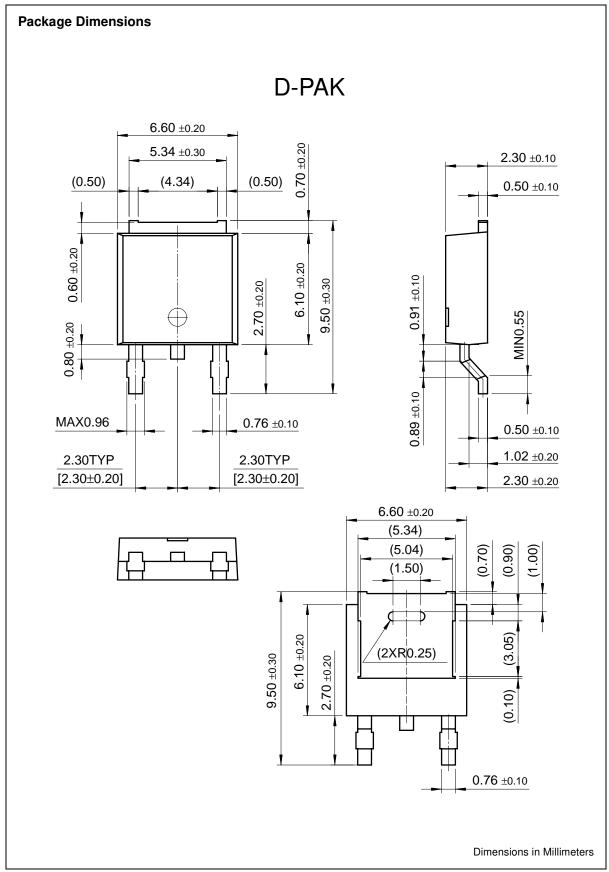


Peak Diode Recovery dv/dt Test Circuit & Waveforms



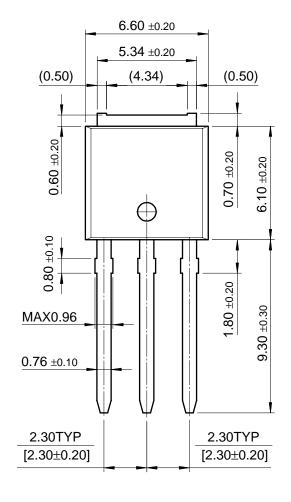


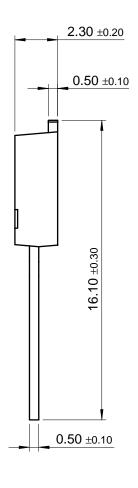
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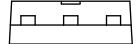




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Dimensions in Millimeters

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	Product	Product status	Pricing*	Package type	Leads	Packing method
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 $Product\ Folder\ -\ Fairchild\ P/N\ IRFU310B\ -\ 400V\ N-Channel\ B-FET\ /\ Substitute\ of\ IRFU310\ \&\ IRFU310A$

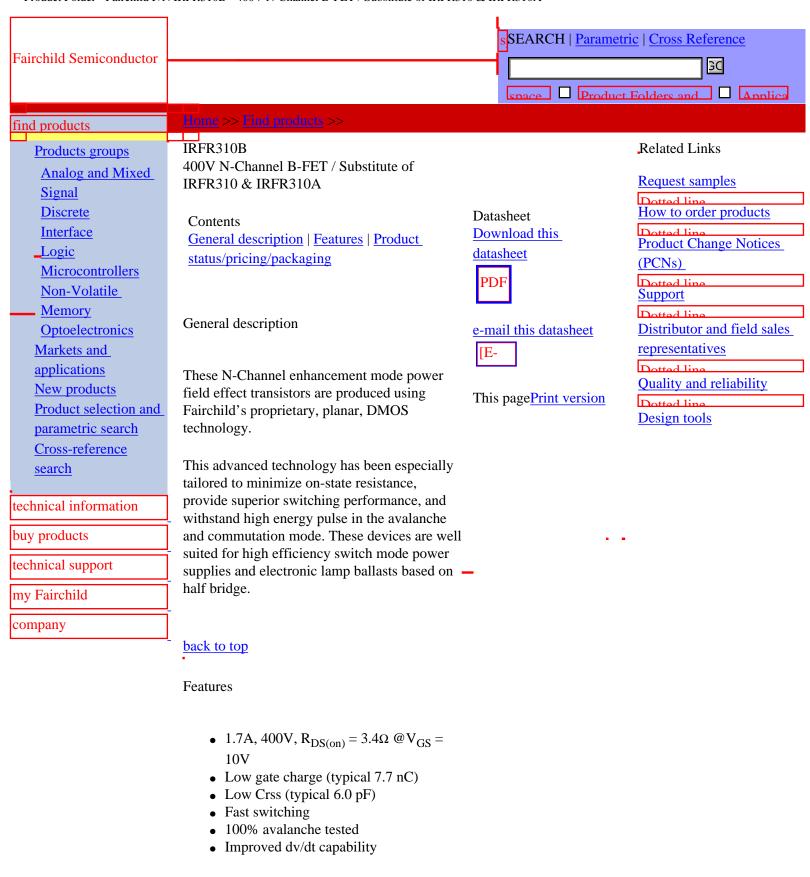
IRFU310BTU	Full Production	\$0.39	TO-251(IPAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method	

IRFR310BTM	Full Production	\$0.418	TO-252(DPAK)	2	TAPE REEL
IRFR310BTF	Full Production	\$0.39	TO-252(DPAK)	2	TAPE REEL

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